

Copper Gleam™ CuPulse™ Plus Acid Copper

High-performance PPR Electroplating

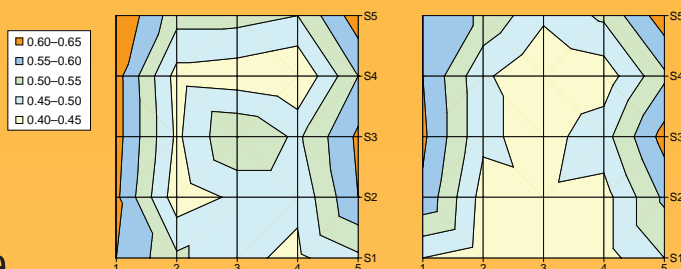
Now available for use with insoluble anodes

- State-of-the-art copper electroplating using reverse pulse plating
- Outstanding throwing power for all board thicknesses
- Full analytical controls

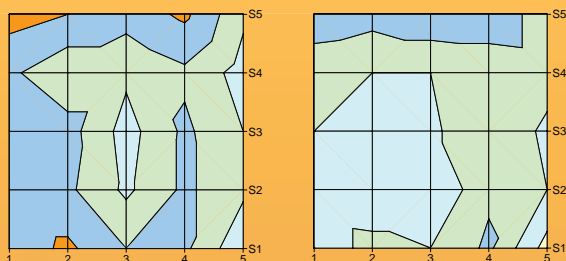
Benefits

- Improved surface distribution
- No downtime for anode maintenance
- Improved bath performance due to by-product oxidation
- Reduced particulates by removal of soluble anodes
- Improved SI control
- Longer bath life

Improved Surface Distribution Soluble Anodes



Insoluble Anodes



Thickness	0.400" (10.2 mm)	0.300" (7.6 mm)	0.187" (4.8 mm)	0.093" (2.4 mm)
DF	6.2	4.5	2.9	0.64
TP	73%	73%	92%	97%
Diameter	0.026" (0.66 mm)	0.020" (0.5 mm)	0.012" (0.3 mm)	0.0135" (0.34 mm)
Time	6 hr. @ 10 ASF	6 hr. @ 10 ASF	90 min. @ 20 ASF	90 min. @ 20 ASF

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